

It is our great pleasure to inform you that we will be introducing our products during the upcoming SEMICON Taiwan 2019 (September 18 - 20, 2019) in Nangang District, Taipei City, Taiwan. At this Exhibition, visitors will be able to see an exhibition of our new product lineup and demonstration of their products. Those who are coming to the exhibition are encouraged to please visit our booth. We are looking forward to seeing you at this exhibition.

Please see the below brief description of the product line that will be introduced during this exhibition.

Dates	September 18[Wed]-20[Fri], 2019 9:00 a.m. – 5:00 p.m.(Last day until 4:00 p.m.)	
Venue	Taipei Nangang Exhibition Center, Taiwan	
Booth No.	TWTC Nangang Hall (4 F) No. L0416 ※ In the booth of Canon Semiconductor Equipment Taiwan, Inc.	
Access	http://www.twtcnangang.com.tw/en/transportation	
Exhibit Products	<p style="text-align: center;">Memory Die bonder</p> <p style="text-align: center;">BESTEM-D531ti</p> 	<p style="text-align: center;">Automated Wire Bonding Inspection Equipment</p> <p style="text-align: center;">BESTEM-V110</p> 
	<p>For any enquiries, please contact us:</p> <p>Canon machinery Inc. SEMICON SYSTEM BUSINESS HQ / SALES DIVISION</p> <p>Tel : +81 77 566 1822 Fax : +81 77 566 1833</p> <p>E-Mail : sales-ml@canon-machinery.co.jp</p>	